

NOTES:

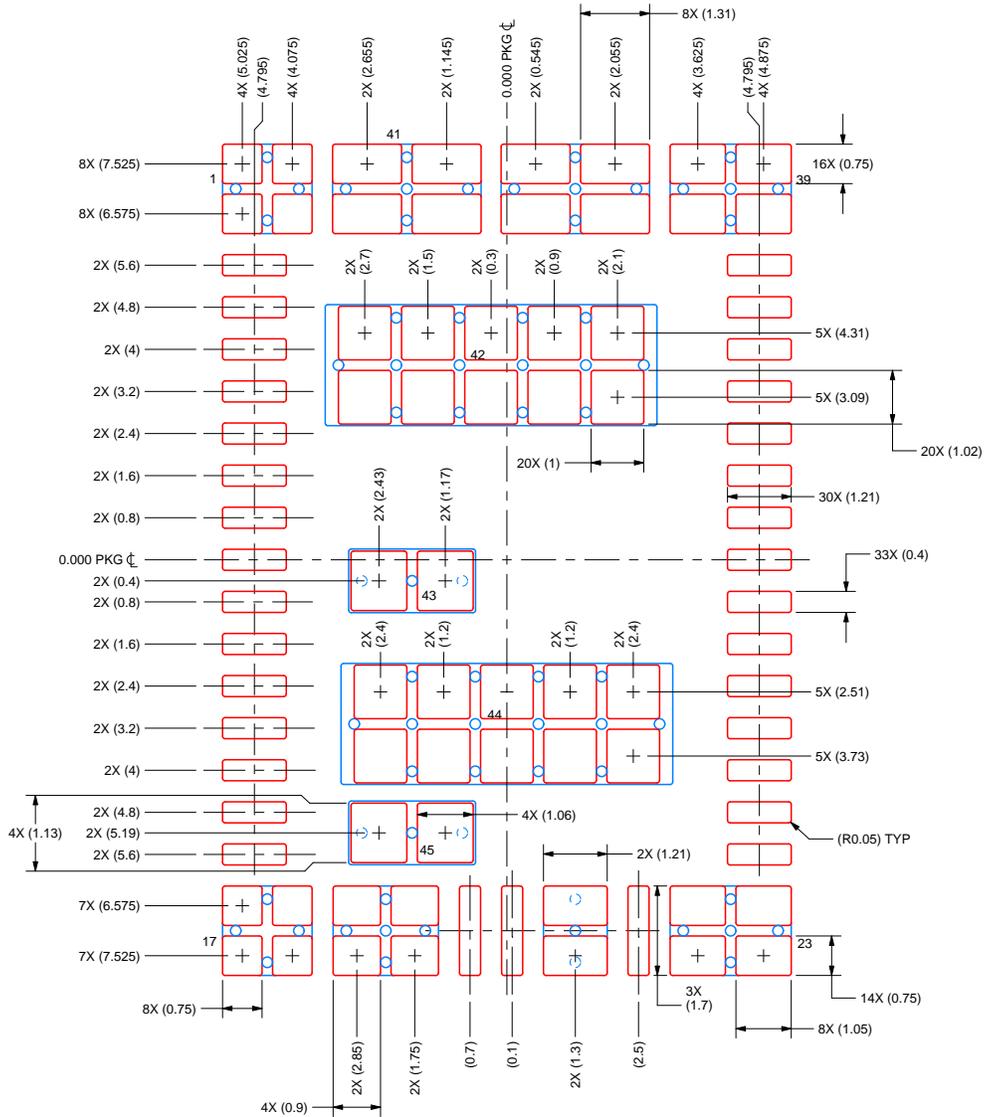
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

EXAMPLE STENCIL DESIGN

MOY0045A

QFM - 4.4 mm max height

QUAD FLATPACK MODULE - NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE: 7X

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 PINS 1 & 17: 78%
 PINS 18, 23 & 39: 80%
 PIN 21: 88%
 PINS 40, 41, 43 & 45: 82%
 PINS 42 & 44: 70%

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